

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 06/09/2022

Details for "TLV70015DSET"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLV70015DSET	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DSE   6	1.5x1.5x0.75	4.8

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Not Categorized	Proprietary Materials		0.000001	0.003343	33	0.000021	0
Precious Metals	Gold	7440-57-5	0.029914	99.996657	999967	0.621228	6212
Sub-Total			<b>0.029915</b>	<b>100</b>	<b>1000000</b>	<b>0.621249</b>	<b>6212</b>
<b>Die Attach Adhesive</b>							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.011773	29.998726	299987	0.244491	2445
Other Inorganic Materials	Silica	7631-86-9	0.001766	4.499936	44999	0.036675	367
Other Organic Materials	Chlorine	7782-50-5	0.000014	0.035673	357	0.000291	3
Thermoplastics	Epoxy	85954-11-6	0.025692	65.465664	654657	0.533549	5335
Sub-Total			<b>0.039245</b>	<b>100</b>	<b>1000000</b>	<b>0.815006</b>	<b>8150</b>
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	1.732537	97.050022	970500	35.979813	359798
Copper and Its Alloys	Iron	7439-89-6	0.046415	2.599989	26000	0.963906	9639
Copper and Its Alloys	Phosphorus	7723-14-0	0.002678	0.150011	1500	0.055614	556
Zinc and Its Alloys	Zinc	7440-66-6	0.00357	0.199978	2000	0.074139	741
Sub-Total			<b>1.7852</b>	<b>100</b>	<b>1000000</b>	<b>37.073472</b>	<b>370735</b>
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.061104	97.300912	973009	1.268954	12690
Precious Metals	Gold	7440-57-5	0.000188	0.299368	2994	0.003904	39
Precious Metals	Palladium	7440-05-3	0.001319	2.100352	21004	0.027392	274
Precious Metals	Silver	7440-22-4	0.000188	0.299368	2994	0.003904	39
Sub-Total			<b>0.062799</b>	<b>100</b>	<b>1000000</b>	<b>1.304155</b>	<b>13042</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	2.231514	84.399998	844000	46.34213	463421
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.138015	5.219983	52200	2.866175	28662
Other Plastics and Rubber	Carbon Black	1333-86-4	0.004759	0.179994	1800	0.098831	988
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.00238	0.090016	900	0.049426	494
Thermoplastics	Epoxy	85954-11-6	0.267306	10.110009	101100	5.551177	55512
Sub-Total			<b>2.643974</b>	<b>100</b>	<b>1000000</b>	<b>54.907739</b>	<b>549077</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.25417	100	1000000	5.27838	52784
Sub-Total			<b>0.25417</b>	<b>100</b>	<b>1000000</b>	<b>5.27838</b>	<b>52784</b>
<b>Total</b>			<b>4.815303</b>			<b>100</b>	<b>1000000</b>

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/econfo](http://www.ti.com/econfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.